

Amendments to the Specification:

Please replace the first paragraph in the application under
REFERENCE TO RELATED APPLICATION with the following amended
paragraph:

The present application is a divisional application of Serial
No. 09/544,263 filed April 6, 2000 entitled METHOD OF MAKING METAL
CORE SUBSTRATE PRINTED CIRCUIT WIRING BOARD ENABLING THERMALLY
ENHANCED BALL GRID ARRAY (BGA) PACKAGES, which is based on
provisional application No. 60/128,948 filed April 13, 1999.